

## **Quarterly Reliability Monitoring Results**

## Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		PTVS28VS1UTR Part Description						
								Nexperia DHAM
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
			TEST					
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours			_		
# A1	Preconditioning	Reflow soldering	3 cycles	438	24630	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage	1000 hours	166	10040	0		
# DI	Bid3	Teverse voltage	1000 110015	100	10040	U		
	тс	JESD22-A104						
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	131	7760	0		
,, ,,,	, , ,	- ,	1000 0,000	101	,,,,,			
	UHAST	JESD22-A118						
# A3 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	131	7760	0		
		JESD22-A102						
	AC	Tamb = 121 °C, RH = 100 %						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)						
	H3TRB	JESD22-A101						
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of						
# A2 alt	Temperature Reverse Bias	rated reverse voltage <sup>[1]</sup>	1000 hours	131	7760	0		
		MIL-STD-750 Method 1037						
	IOL	ton = toff, devices powered to insure $\Delta Tj$ =						
# A5	Intermittent Operating Life	100 -C 101 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
	neu	JECD22 A111						
# 60	RSH Resistance to Solder Heat	JESD22-A111	10 -	45	1250	0		
# C8	SD Resistance to Solder Heat	200 C ± 3 ·C	10 s	45	1350	0		
# C10	Solderability	J-STD-002		111	1110	0		
# CIU	Solderability	3 310 002		111	1110	U		

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	10040	0	0,42	2,36E+09

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